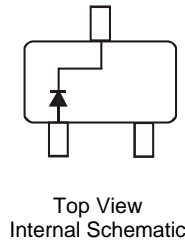


## Features

- Fast Switching Speed
- Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

## Mechanical Data

- Package: SOT323
- Package Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208<sup>(e3)</sup>
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

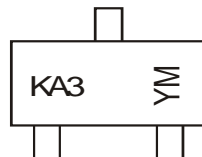


## Ordering Information (Notes 4, 5)

Orderable Part Number	Package	Packing	
		Quantity	Carrier
MMBD4448W-7-F	SOT323	3,000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.
  5. Product manufactured with Green Molding Compound and do not contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.

## Marking Information



KA3 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: L = 2024)  
 M = Month (ex: O = October)  
 A Bar around the Date Code Marking Denotes AT Site

### Date Code Key

Year	2002	...	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	N	...	J	K	L	M	N	P	R	S	T	U
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	75	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current (Note 6)	I <sub>FM</sub>	500	mA
Non-Repetitive Peak Forward Surge Current		@ t = 1.0μs	4.0
		@ t = 1.0ms	1.0

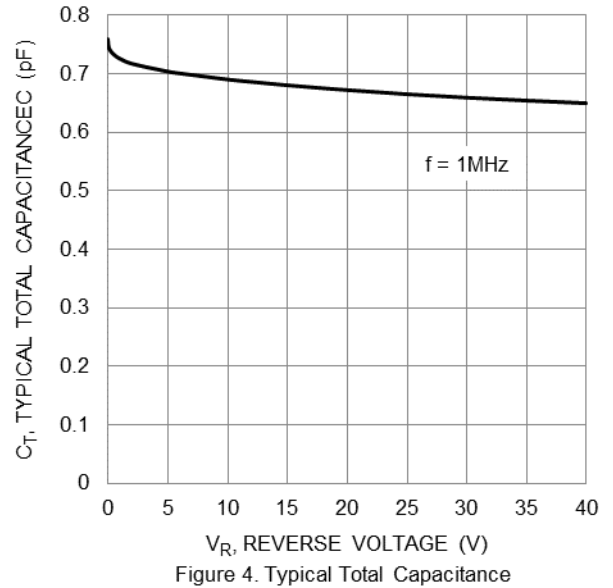
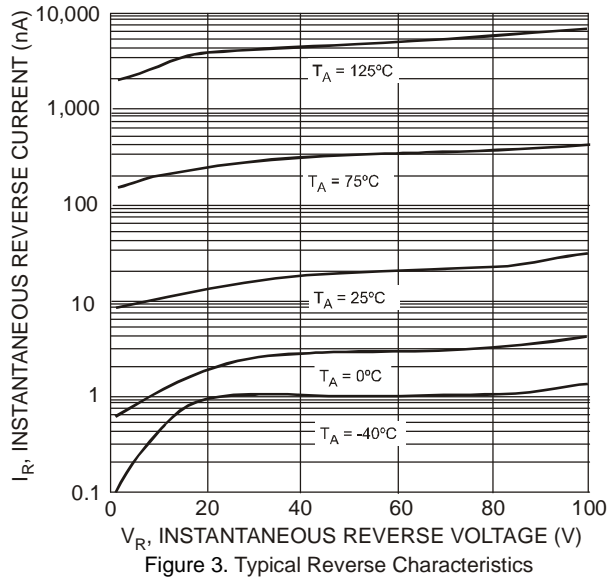
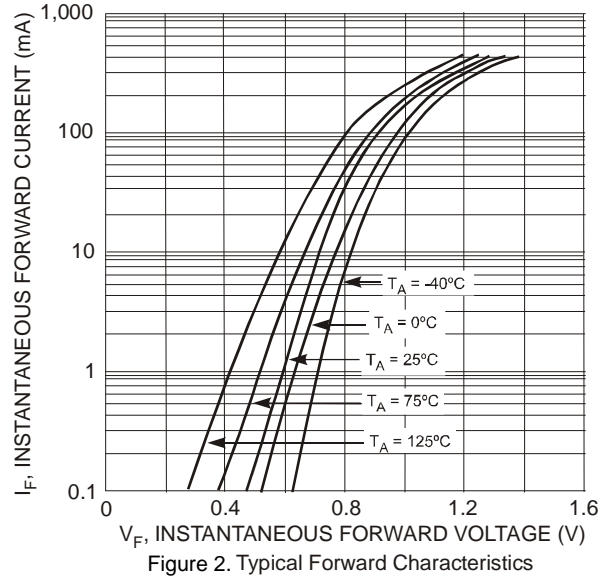
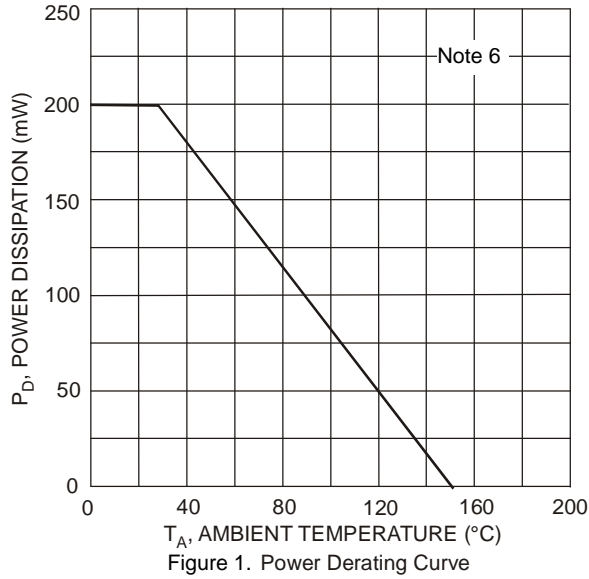
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P <sub>D</sub>	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 10μA
Forward Voltage	V <sub>F</sub>	0.62	0.72	V	I <sub>F</sub> = 5.0mA
		—	0.855		I <sub>F</sub> = 10mA
		—	1.0		I <sub>F</sub> = 100mA
		—	1.25		I <sub>F</sub> = 150mA
Reverse Current (Note 7)	I <sub>R</sub>	—	1.0	μA	V <sub>R</sub> = 75V
		—	50	μA	V <sub>R</sub> = 75V, T <sub>J</sub> = +150°C
		—	30	μA	V <sub>R</sub> = 25V, T <sub>J</sub> = +150°C
		—	25	nA	V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 6. Device mounted on FR-4 PCB, 1 inch square, 2oz copper pad layout.  
7. Short duration pulse test used to minimize self-heating effect.

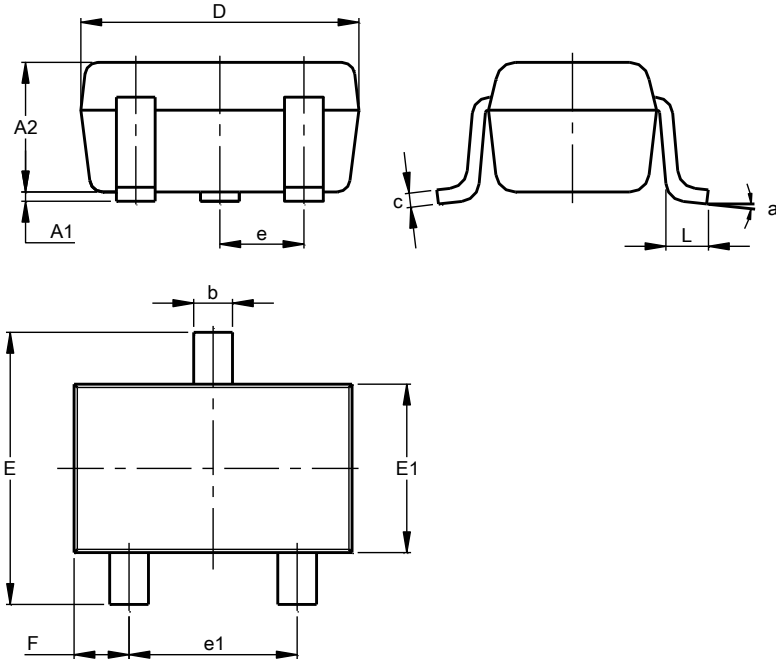


Note: 6. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062inch; pad layout as shown on Diodes Incorporated's suggested pad layout document, which can be found on our website at <http://www.diodes.com/package-outlines.html>.

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT323**

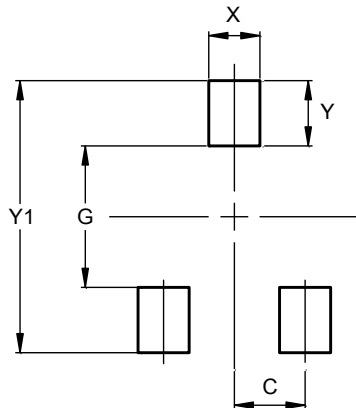


SOT323			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT323**



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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